

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT								
NATURE OF CONVEYANCE:	ASSIGNMENT								
CONVEYING PARTY DATA									
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>JUNYA TAKAHASHI</td> <td>11/08/2013</td> </tr> <tr> <td>MAKOTO YAMAKADO</td> <td>11/08/2013</td> </tr> <tr> <td>SHINJIRO SAITO</td> <td>11/18/2013</td> </tr> </tbody> </table>		Name	Execution Date	JUNYA TAKAHASHI	11/08/2013	MAKOTO YAMAKADO	11/08/2013	SHINJIRO SAITO	11/18/2013
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<table border="1"> <tr> <td>Name:</td> <td>HITACHI AUTOMOTIVE SYSTEMS, LTD.</td> </tr> <tr> <td>Street Address:</td> <td>2520, TAKABA</td> </tr> <tr> <td>City:</td> <td>HITACHINAKA-SHI, IBARAKI</td> </tr> <tr> <td>State/Country:</td> <td>JAPAN</td> </tr> </table>		Name:	HITACHI AUTOMOTIVE SYSTEMS, LTD.	Street Address:	2520, TAKABA	City:	HITACHINAKA-SHI, IBARAKI	State/Country:	JAPAN
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CORRESPONDENCE DATA									
<p>Fax Number: (202)672-5399 Phone: 2026725300 Email: ipdocketing@foley.com <i>Correspondence will be sent via US Mail when the email attempt is unsuccessful.</i> Correspondent Name: FOLEY & LARDNER, LLP Address Line 1: 3000 K ST., NW Address Line 2: SUITE 600 Address Line 4: WASHINGTON, DISTRICT OF COLUMBIA 20007</p>									
ATTORNEY DOCKET NUMBER:	091442-0203								
NAME OF SUBMITTER:	P. SHIEK FOR W. T. ELLIS								
Signature:	/P. SHIEK/								
Date:	02/03/2014								
Total Attachments: 1 source=assign#page1.tif									

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ASSIGNMENT (譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me by Hitachi Automotive Systems, Ltd., a corporation organized under the laws of Japan, located at 2520, Takaba, Hitachinaka-shi, Ibaraki Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said Hitachi Automotive Systems, Ltd., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

VEHICLE MOTION CONTROL APPARATUS AND VEHICLE MOTION CONTROL SYSTEM

Invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted,

to be held and enjoyed by said Hitachi Automotive Systems, Ltd., its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Hitachi Automotive Systems, Ltd.,

Signed on the date(s) indicated aside our signatures:

INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
1) <u>Junya Takahashi</u> Junya TAKAHASHI	<u>11/08/2013</u>
2) <u>Makoto Yamakado</u> Makoto YAMAKADO	<u>11/08/2013</u>
3) <u>Shinjiro Saito</u> Shinjiro SAITO	<u>11/18/2013</u>
4) _____	_____
5) _____	_____
6) _____	_____
7) _____	_____
8) _____	_____
9) _____	_____
10) _____	_____

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